

MH181 Specifications General-Purpose Hall Effect Latch Effect Latch

MH181, Hall-Effect sensor, designed for electronic commutation of brush-less DC motor applications. The device includes an on-chip Hall voltage generator for magnetic sensing, a comparator that amplifies the Hall Voltage, and a Schmitt trigger to provide switching hysteresis for noise rejection, and open collector output. An internal band gap regulator is used to provide temperature compensated supply voltage for internal circuits and allows a wide operating supply range. The device is identical except for magnetic switch points.

The device includes on a single silicon chip a voltage regulator, Hall-voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, open-collector output to sink up to 25mA. A south pole of sufficient strength will turn the output on. The North Pole is necessary to turn the output off. An on-board regulator permits operation with supply voltages of 3.5V to 20 V.

The package type is in a lead Halogen Free version was verified by third party organization.

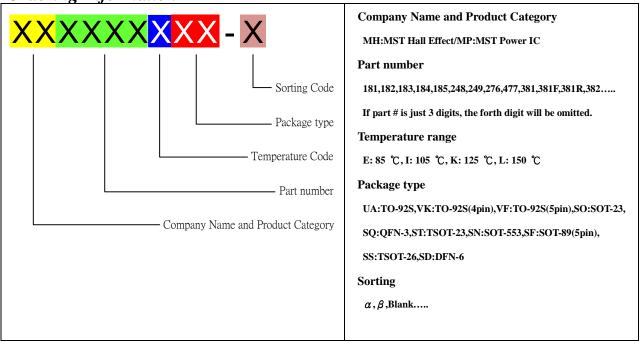
Features and Benefits

- Temperature compensation.
- Wide operating voltage range.
- Open-Collector pre-driver.
- Reverse bias protection on power supply pin.
- 100% at 125°C "Hot Test" in MH181KUA

Applications

- High temperature Hall IC application
- Fan motor application
- BLDC motor application
- 3 phase BLDC motor in "K" Spec

Ordering Information





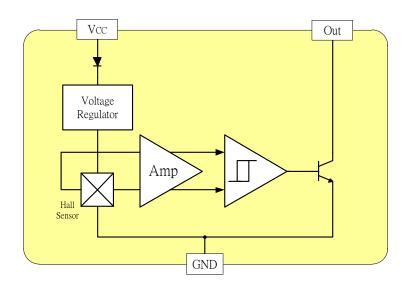
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Part No.	Temperature Suffix	Package Type	
MH181KUA	K $(-40^{\circ}\text{C to} + 125^{\circ}\text{C})$	UA (TO-92S)	
MH181EUA	E $(-40^{\circ}\text{C to} + 85^{\circ}\text{C})$	UA (TO-92S)	
MH181ESO	E $(-40^{\circ}\text{C to} + 85^{\circ}\text{C})$	SO (SOT-23)	

MH 181KUA is developed as "125 degree C Temperature Version" by MST technology. Major application is industrial and automotive.

Functional Diagram

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Absolute Maximum Ratings At (Ta=25°C)

Characteristics		Values	Unit	
Supply voltage, (Vcc)		20	V	
Output Voltage,(Vout)		30	V	
Reverse voltage, (Vcc) (Vour)	-20	V		
Magnetic flux density		Unlimited	Gauss	
Output current, (IovT)		25	mA	
	"E" version	-20 to +85	°C °C	
Operating Temperature Range, (Ta	"K" version	-40 to +125		
Storage temperature range, (Ts)		-55 to +150	$^{\circ}$ C	
Maximum Junction Temp, (<i>Tj</i>)		150	°C	
The amount Description on	$(heta_{ja})$ UA	206	°C/W	
Thermal Resistance	$(heta_{jc})$ UA	148	°C/W	
Package Power Dissipation, (P_D)		606	mW	

Note: Do not apply reverse voltage to V_{CC} and V_{OUT} Pin, It may be caused for Miss function or damaged device.



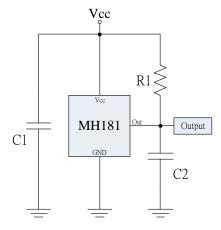
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Electrical Specifications

DC Operating Parameters : $Ta=+25 \, ^{\circ}C$, Vcc=12V

Parameters	Test Conditions	Min	Тур	Max	Units
Supply Voltage,(Vcc)	Operating	3.5		20.0	V
Supply Current,(Icc)	B <b<sub>OP</b<sub>		4.0	8.0	mA
Output Saturation Voltage,(V _{Sat})	IOUT = 10 mA, B>BOP			700.0	mV
Output Leakage Current,(Ioff)	IOFF B <brp, vout="12V</td"><td></td><td></td><td>10.0</td><td>uA</td></brp,>			10.0	uA
Output Rise Time,(<i>T_R</i>)	RL=820Ω, CL =20pF			1.5	uS
Output Fall Time, (T_F)	RL=820Ω; CL =20pF			1.5	uS
Operate Point,(BoP)	UA(SO)	5(-90)		90(-5)	Gauss
Release Point,(BRP)	UA(SO)	-90 (5)		-5 (90)	Gauss
Hysteresis,(BHYS)			100		Gauss

Typical application circuit



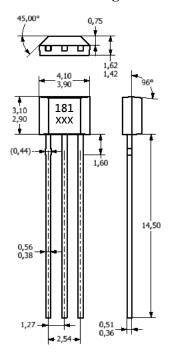
C1: 1000PF

C2: 15PF

 $R1:10K\Omega$

Sensor Location, Package Dimension and Marking MH181 Package

UA Package

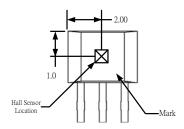


NOTES:

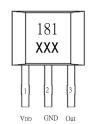
- 1).Controlling dimension: mm
- 2).Leads must be free of flash and plating voids
- Do not bend leads within 1 mm of lead to package interface.
- 4).PINOUT:

Pin 1 VCC
Pin 2 GND
Pin 3 Output

Hall Chip location



Output Pin Assignment (Top view)

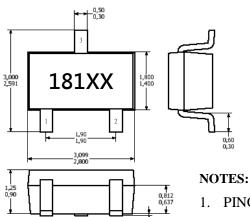


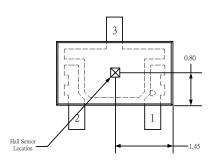


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SO Package (Top View)

Hall Plate Chip Location (Bottom view)





- 1. PINOUT (See Top View at left :)
 - Pin 1 V_{CC}
 - Pin 2 Output
 - Pin 3 **GND**
- 2. Controlling dimension: mm
- 3. Lead thickness after solder plating will be 0.254mm maximum